



DMN4020LFDE

Product Summary

BV _{DSS}	R _{DS(ON)} max	l _D max T _A = +25°C
	$20m\Omega @ V_{GS} = 10V$	8.0A
40V	$28m\Omega @ V_{GS} = 4.5V$	6.7A

Description and Applications

This new generation MOSFET has been designed to minimize the onstate resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions

40V N-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

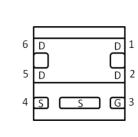
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Low On-Resistance
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

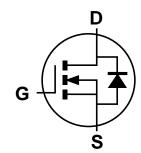
- Case: U-DFN2020-6 (Type E)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208^(A)
- Weight: 0.0065 grams (Approximate)

U-DFN2020-6 (Type E)

Bottom View



Pin Out



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Quantity Per Reel
DMN4020LFDE-7	NE	7	3,000
DMN4020LFDE-13	NE	13	10,000

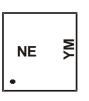
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



NE = Product Type Marking Code YM = Date Code Marking Y = Year (ex: E = 2017) M = Month (ex: 9 = September)

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Date	Code	ĸev

Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Y		Z		А	E	3	С		D		E
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	40	V		
Gate-Source Voltage			V _{GSS}	±20	V
	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	Ι _D	8.0 6.3	А
Continuous Drain Current (Note 6) V_{GS} = 10V	t < 10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	Ι _D	9.5 7.5	А
	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	Ι _D	6.7 5.3	А
Continuous Drain Current (Note 6) V_{GS} = 4.5V	t < 10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	8.0 6.4	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	I _{DM}	32	А		
Maximum Body Diode Continuous Current	ls	2.5	А		

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Total Power Dissipation (Note 5)	T _A = +25°C	T _A = +25°C		W	
Total Power Dissipation (Note 5)	T _A = +70°C	PD	0.42	vv	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	P	189	°C/W	
Thermal Resistance, sunction to Ambient (Note 5)	t < 10s	$R_{ extsf{ heta}JA}$	132	C/W	
Total Power Dissipation (Note 6)	T _A = +25°C	Р	2.03	W	
Total Power Dissipation (Note 6)	$T_A = +70^{\circ}C$	PD	1.31		
Thermal Registeres, Junction to Ambient (Note 6)	Steady State	P	61	°C/W	
Thermal Resistance, Junction to Ambient (Note 6)	t < 10s	$R_{ extsf{ heta}JA}$	43		
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	9.3			
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C	

Electrical Characteristics ($@T_A = +25^{\circ}C$, unless otherwise specified.)

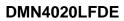
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	40	_	_	V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}		_	1	μA	$V_{DS} = 40V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1.4	_	2.4	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance			15	20	mΩ	$V_{GS} = 10V, I_D = 8A$
	R _{DS(ON)}		20	28	11152	$V_{GS} = 4.5V, I_D = 4A$
Diode Forward Voltage	V _{SD}		0.7	1	V	$V_{GS} = 0V, I_{S} = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{iss}	_	1060		pF	
Output Capacitance	Coss	_	84	—	pF	− V _{DS} = 20V, V _{GS} = 0V, − f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}		58	_	рF	1 = 1.000012
Gate Resistance	Rg		1.6	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg		8.8	_	nC	
Total Gate Charge (V _{GS} = 10V)	Qg		19.1	_	nC	V 20V I 8A
Gate-Source Charge	Q _{gs}		3.0	_	nC	$V_{DS} = 20V, I_D = 8A$
Gate-Drain Charge	Q _{gd}	_	2.5	_	nC	
Turn-On Delay Time	t _{D(ON)}	_	5.3	—	ns	
Turn-On Rise Time	t _R	_	7.1		ns	$V_{DS} = 20V, R_{L} = 2.5\Omega$
Turn-Off Delay Time	t _{D(OFF)}	_	15.1	—	ns	$V_{GS} = 10V, R_G = 3\Omega$
Turn-Off Fall Time	tF	_	4.8	—	ns]
Reverse Recovery Time	t _{RR}		10.5	_	ns	
Reverse Recovery Charge	Q _{RR}		4.15		nC	I _F = 8A, di/dt = 100A/μs

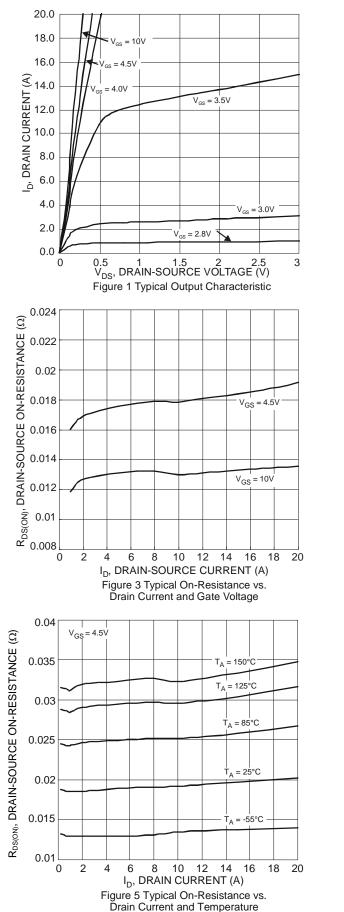
Notes:

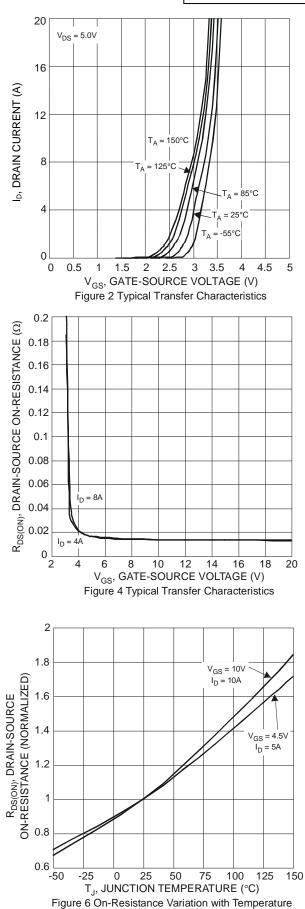
Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
Short duration pulse test used to minimize self-heating effect.

8. Guaranteed by design. Not subject to production testing.







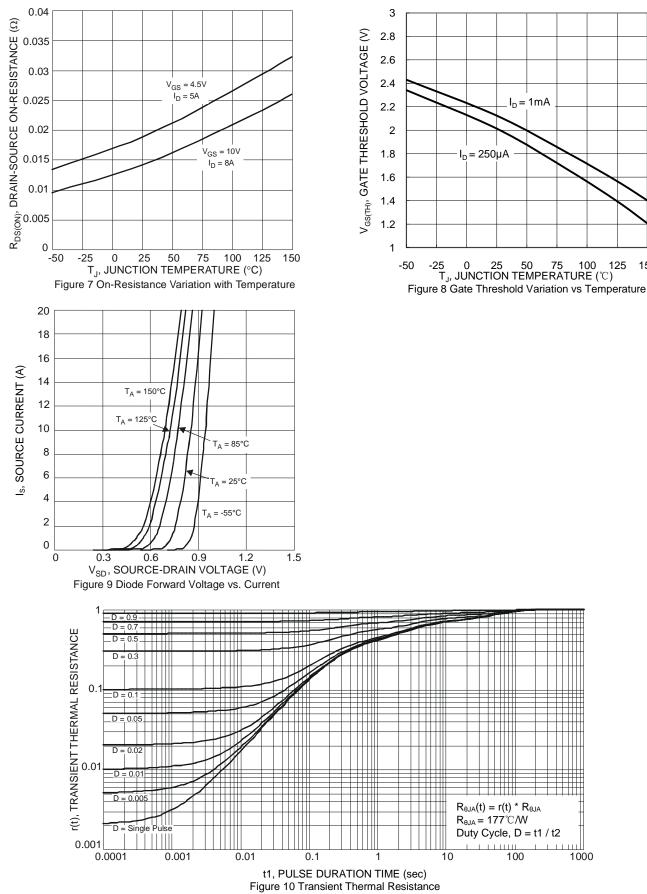






125

150

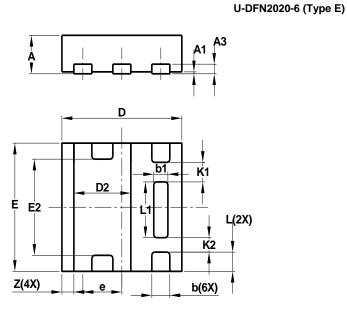


1000



Package Outline Dimensions

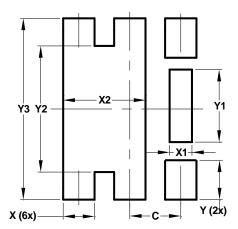
Please see http://www.diodes.com/package-outlines.html for the latest version.



	U-DFN2020-6 Type E							
Dim	Min	Min Max Ty						
Α	0.57	0.63	0.60					
A1	0	0.05	0.03					
A3			0.15					
b	0.25	0.35	0.30					
b1	0.185	0.285	0.235					
D	1.95	2.05	2.00					
D2	0.85	1.05	0.95					
E	1.95	2.05	2.00					
E2	1.40	1.60	1.50					
е			0.65					
L	0.25	0.35	0.30					
L1	0.82	0.92	0.87					
K1	_		0.305					
K2	_		0.225					
Z	_		0.20					
All	Dimens	ions in r	nm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



U-DFN2020-6 (Type E)

Dimensions	Value (in mm)
С	0.650
Х	0.400
X1	0.285
X2	1.050
Y	0.500
Y1	0.920
Y2	1.600
Y3	2.300

Datasheet number: DS35819 Rev. 4 - 2

DMN4020LFDE



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